

REPORT DOCUMENTATION PAGE

Form Approved
OMB NO. 0704-0188

Public Reporting burden for this collection of information is estimated to average 1 hour per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the collection of information. Send comment regarding this burden estimates or any other aspect of this collection of information, including suggestions for reducing this burden, to Washington Headquarters Services, Directorate for information Operations and Reports, 1215 Jefferson Davis Highway, Suite 1204, Arlington, VA 22202-4302, and to the Office of Management and Budget, Paperwork Reduction Project (0704-0188,) Washington, DC 20503.

1. AGENCY USE ONLY (Leave Blank)		2. REPORT DATE 5/14/02	3. REPORT TYPE AND DATES COVERED Final Report 1 July 01 to 28 Feb 02	
4. TITLE AND SUBTITLE A Palm Size Micron-gap ThermoPhoto Voltaic (MTPV) Energy Converter			5. FUNDING NUMBERS DAAD19-01-C-0064	
6. AUTHOR(S) Robert DiMatteo, Program Manager			\$500,000.00	
7. PERFORMING ORGANIZATION NAME(S) AND ADDRESS(ES) C. S. Draper Laboratory 555 Technology Sqr. Cambridge, MA 02139			8. PERFORMING ORGANIZATION REPORT NUMBER Palm Final Report #09	
9. SPONSORING / MONITORING AGENCY NAME(S) AND ADDRESS(ES) U. S. Army Research Office P.O. Box 12211 Research Triangle Park, NC 27709-2211			10. SPONSORING / MONITORING AGENCY REPORT NUMBER 42651.1-CH	
11. SUPPLEMENTARY NOTES The views, opinions and/or findings contained in this report are those of the author(s) and should not be construed as an official Department of the Army position, policy or decision, unless so designated by other documentation.				
12 a. DISTRIBUTION / AVAILABILITY STATEMENT Approved for public release; distribution unlimited.			12 b. DISTRIBUTION CODE	
13. ABSTRACT (Maximum 200 words) The goal of this project was to demonstrate that enhanced photovoltaic cell output can be achieved as a function of the physical gap between emitter and receiver in a Micron-gap ThermoPhoto Voltaic (MTPV) system. This was successfully demonstrated. Test specimen assemblies were first built for small gap MTPV testing. Tests were then performed with 0.2 micron gap heater chips on InGaAs photovoltaic cells provided by Dave Wilt of NASA Glenn. Small gap (down) and large gap (up) experiments at 300°C, 400°C, and 500°C were performed. Measurements with 0.2 micron gap heater chips were also made with 0.74 eV GaSb photovoltaic cells supplied by EdTek. In all conditions greater than 100% enhancement was measured. In both small gap ("DOWN") and large gap ("UP") positions heater power was shut off and the short circuit currents did not shut off but thermally decayed demonstrating that the short circuit current enhancement demonstrated were not artifacts of the heater electrical power.				
14. SUBJECT TERMS Micron-gap ThermoPhoto Voltaic (MTPV)			15. NUMBER OF PAGES 9	
			16. PRICE CODE	
17. SECURITY CLASSIFICATION OR REPORT UNCLASSIFIED	18. SECURITY CLASSIFICATION ON THIS PAGE UNCLASSIFIED	19. SECURITY CLASSIFICATION OF ABSTRACT UNCLASSIFIED	20. LIMITATION OF ABSTRACT UL	

NSN 7540-01-280-5500

Standard Form 298 (Rev.2-89)
Prescribed by ANSI Std. Z39-18
298-102

**A Palm Size Micron-gap ThermoPhoto Voltaic (MTPV)
Energy Converter**

Final Progress Report

Report - 09

Prepared for:

Dr. Robert Nowak

rnowak@darper.mil

Defense Advanced Research Project DSO

3701 N. Fairfax Drive

Arlington, VA 02203-1714

Contract No.

DAAD19-01-C-0064

This report is **Unclassified**

March 26, 2002

The Charles Stark Draper Laboratory, Inc.

555 Technology Square

Cambridge, Massachusetts 02139-3563

1.0 List of Appendixes, Illustrations and Tables

Illustrations

1. Experimental Configuration of Heater Chip and PV Cell
2. 0.2 Micron Heater Chip, Large Gap – Small Gap Data – 300°C – on InGaAs Cell
3. 0.2 Micron Heater Chip, Large Gap – Small Gap Data – 400°C – on InGaAs Cell
4. 0.2 Micron Heater Chip, Large Gap – Small Gap Data – 500°C – on InGaAs Cell
5. 0.4 Micron Heater Chip, Large Gap – Small Gap Data – 400°C – on InGaAs Cell
6. 0.2 Micron Heater Chip, Large Gap – Small Gap Data – 500-600°C – on GaSb Cell
7. Heater Power Off Test – Small Gap
8. Heater Power Off Test – Large Gap

2.0 Statement of the Problem Studied

The goal of this project was to demonstrate that enhanced photovoltaic cell output can be achieved as a function of the physical gap between emitter and receiver in an MTPV system. This was successfully demonstrated in this project.

2.0 Summary of Most Important Results

Test specimen assemblies were first built for small gap MTPV testing. This fixturing which was used for the testing reported below is shown in Illustration 1.

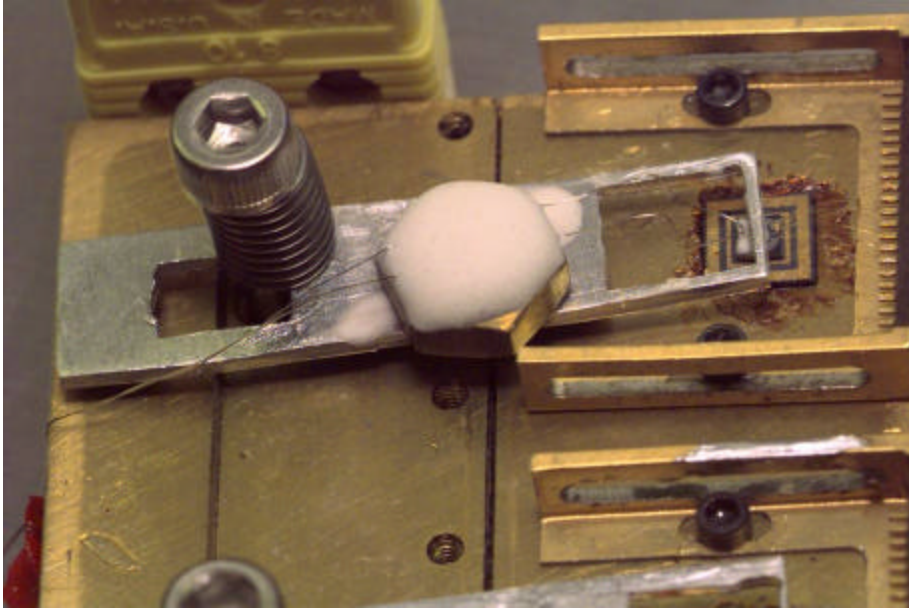


Illustration 1. Experimental Configuration of Heater Chip and PV Cell

Tests were performed with 0.2 micron gap heater chips on InGaAs photovoltaic cells provided by Dave Wilt at NASA Glenn. Results for small gap (down) and large gap (up) experiments at 300°C, 400°C, and 500°C are shown below in Illustrations 2, 3, 4, and 5.

9/14-17/01 11B 0.2u gap NASA InGaAs cell photocurrent at 300 degrees C

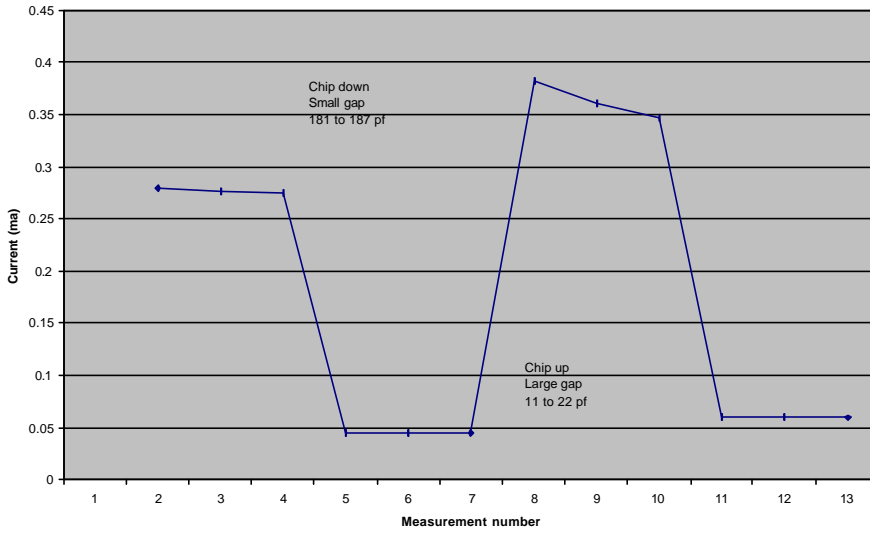


Illustration 2. 0.2 Micron Heater Chip, Large Gap – Small Gap Data – 300°C – on InGaAs Cell

9/14-17/01 11B 0.2u gap NASA InGaAs cell photocurrent at 400 degrees C

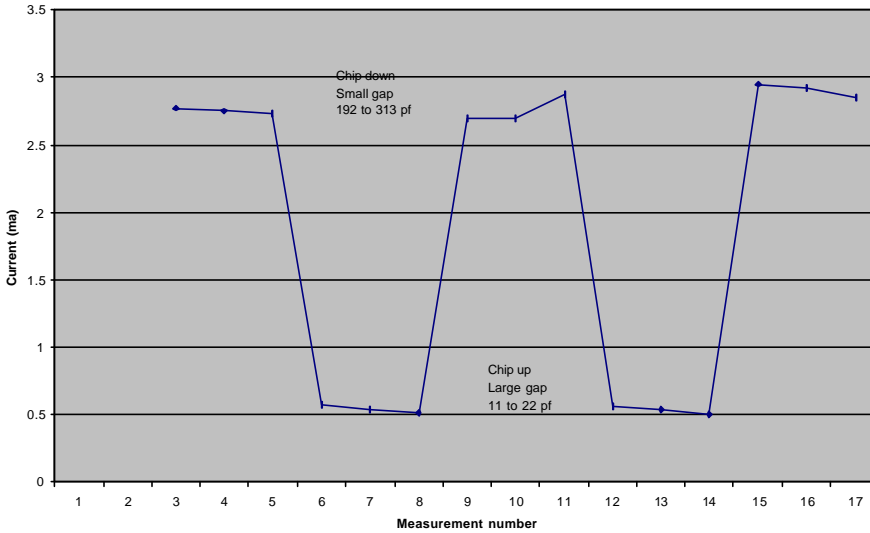


Illustration 3. 0.2 Micron Heater Chip, Large Gap – Small Gap Data – 400°C – on InGaAs Cell

9/14-17/01 11B 0.2u gap NASA InGaAs cell photocurrent at 500 degrees C

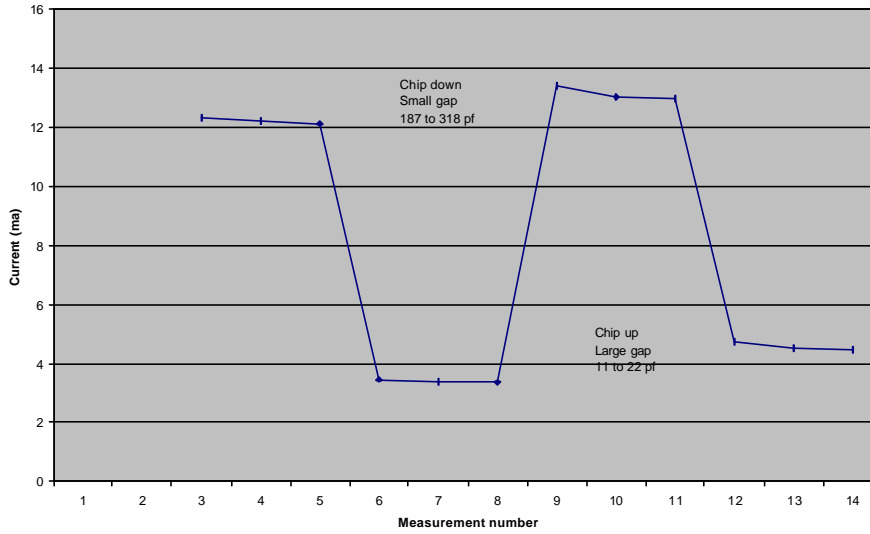


Illustration 4. 0.2 Micron Heater Chip, Large Gap – Small Gap Data – 500°C – on InGaAs Cell

DRAPER-DARPA PALM POWER MTPV DATA
11/2/01 7A 0.4u gap NASA InGaAs cell photocurrent at 400 degrees C

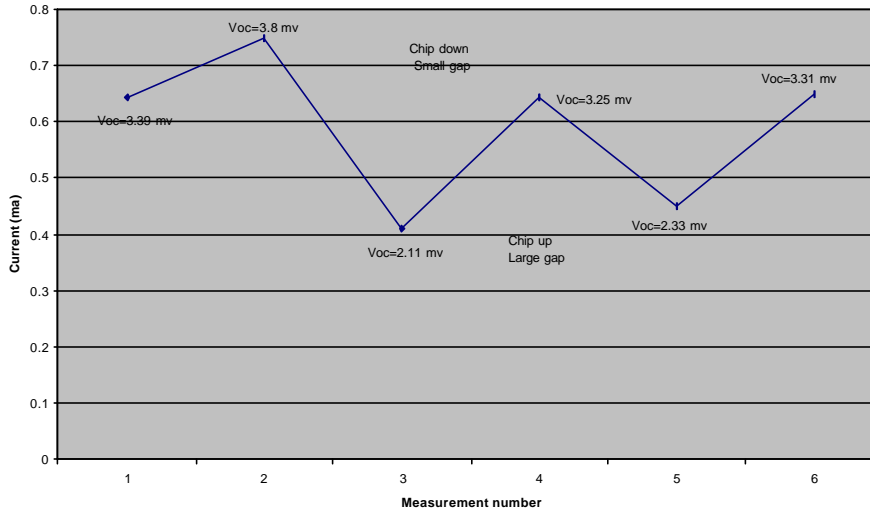


Illustration 5. 0.4 Micron Heater Chip, Large Gap – Small Gap Data – 400°C – on InGaAs Cell

Measurements with 0.2 micron gap heater chips were also made with 0.74 eV GaSb photovoltaic cells supplied by EdTek. The results are shown below in Illustration 6.

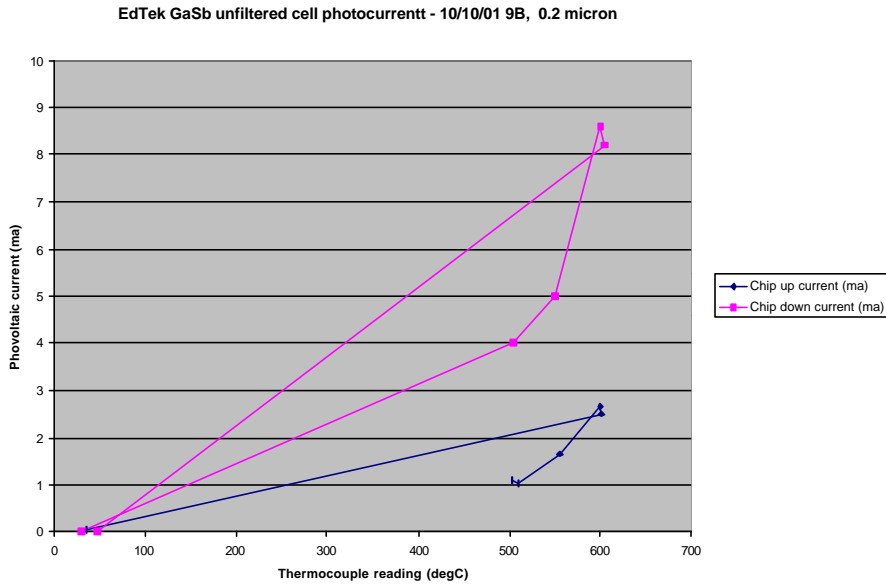


Illustration 6. 0.2 Micron Heater Chip, Large Gap – Small Gap Data – 500-600°C– on GaSb Cell

Illustrations 7 and 8 show the results of Heater Chip Power Off testing. In both small gap (“DOWN”) and large gap (“UP”) positions heater power (yellow lines) was shut off and the short circuit currents (green lines) did not shut off but thermally decayed demonstrating that the short circuit current enhancement demonstrated in Illustrations 2-6 were not artifacts of the heater electrical power.

DOWN

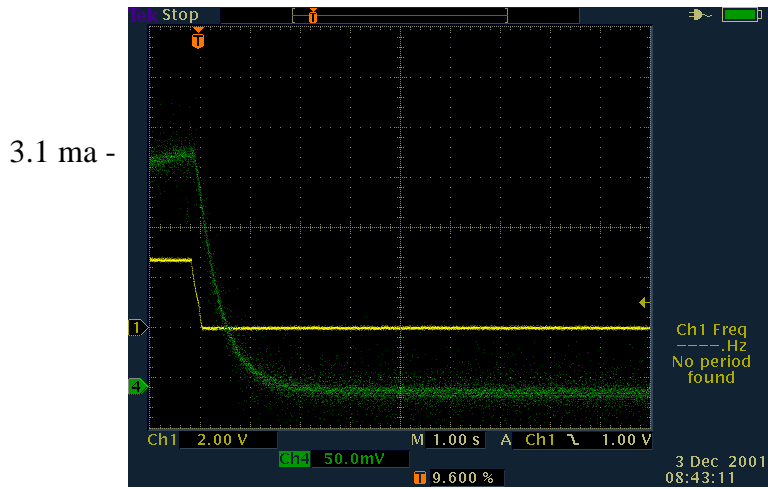


Illustration 7. Heater Power Off Test – Small Gap

UP

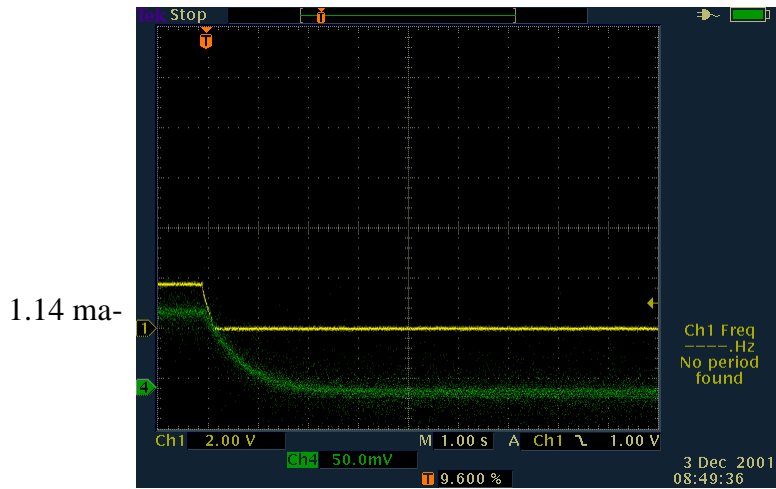


Illustration 8. Heater Power Off Test – Large Gap

4.0 Listing of Publications

A paper summarizing these results is being considered for submission to Applied Physics Letters for publication.

5.0 List of all participating scientific personnel etc.

6.0 Report of inventions

None were made under this contract.

7.0 Bibliography

None

8.0 Appendixes

None